



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-07-16
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC572L64E3BC6AR	A9YE*FE64ACQ	A	1054	2018-07-16
Amount	UoM	Unit type	ST ECOPACK Grade	
520.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14-14-1	100	gull wing	
Comment	TQFP 100 14x14x1.0 1.0 ExpadDown			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

California 65 list			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.68	Die - Leadframe	3235

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	A9YE*FE64ACQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	36.061	mg	supplier	die	Silicon (Si)	7440-21-3		35.505	mg	984582	68279
				supplier	metallization	Aluminium (Al)	7429-90-5		0.039	mg	1082	75
				supplier	metallization	Copper (Cu)	7440-50-8		0.233	mg	6460	447
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	28	2
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.038	mg	1054	73
				supplier	metallization	Titanium (Ti)	7440-32-6		0.010	mg	277	19
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	55	4
				supplier	Passivation	Silicon Nitride	12033-89-5		0.053	mg	1470	102
				supplier	Passivation	Silicon Oxide	7631-86-0		0.180	mg	4992	346
				supplier	alloy	Copper (Cu)	7440-50-8		218.216	mg	990383	419646
				supplier	alloy	Iron (Fe)	7439-89-6		0.219	mg	994	421
Leadframe	M-004 Copper and its alloys	220.335	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.066	mg	300	127
				supplier	metallization	Nickel (Ni)	7440-02-0		1.681	mg	7629	3233
				supplier	metallization	Palladium (Pd)	7440-05-3		0.108	mg	490	208
				supplier	metallization	Gold (Au)	7440-57-5		0.045	mg	204	87
				supplier	glue	Silver (Ag)	7440-22-4		4.320	mg	894966	8308
				supplier	glue	isobornyl Methacrylate	7534-94-3		0.362	mg	74995	696
				supplier	glue	Bismaleimide resin	Proprietary		0.145	mg	30039	279
				supplier	wire	Copper (Cu)	7440-50-8		0.833	mg	1000000	1602
				supplier	mold compound	Silica, vitreous	60676-86-0		222.863	mg	863998	428583
				supplier	mold compound	Epoxy Resin	25068-38-6		19.346	mg	75000	37204
				Encapsulation	M-011 Other inorganic materials	257.944	mg	supplier	mold compound	Phenol Resin	29690-82-2	
supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0						1.290	mg	5001	2481
supplier	mold compound	Quartz	14808-60-7						0.774	mg	3001	1488
supplier	mold compound	Carbon black	1333-86-4						0.774	mg	3001	1488
supplier	mold compound											